

P-Channel Enhancement Mode Power MOSFET

Description

The PTTT \in J uses advanced trench technology to provide excellent $R_{DS(ON)}$, This device is suitable for use as a load switch or in PWM applications.

General Features

• $V_{DS} = -30V, I_{D} = -15A$

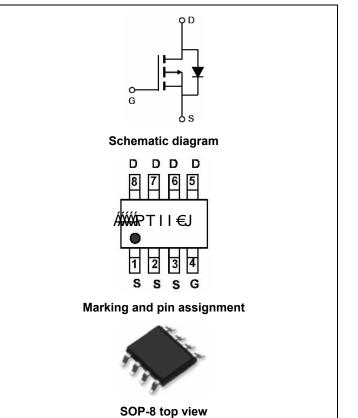
 $R_{DS(ON)}$ < 10m Ω @ V_{GS} =-10V

 $R_{DS(ON)}$ <15m Ω @ V_{GS} =-4.5V

- High power and current handing capability
- Lead free product is acquired
- Surface mount package

Application

- PWM applications
- Load switch
- Uninterruptible power supply



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
PTII€J	PTII€J	SOP-8	Ø330mm	12mm	2500 units

Absolute Maximum Ratings (T_A=25 °Cunless otherwise noted)

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Parameter	Symbol	Limit	Unit			
Drain-Source Voltage	V _{DS}	-30	V			
Gate-Source Voltage	V _G S	±20	V			
Drain Current-Continuous	I _D	-15	Α			
Drain Current-Pulsed (Note 1)	I _{DM}	-80	А			
Maximum Power Dissipation	P _D	3.1	W			
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 150	$^{\circ}$ C			

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	R _{θJA}	40	°C/W
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Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =-250μA	-30	-33	-	V





Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-30V,V _{GS} =0V	-	-	-1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)			•			
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =-250μA	-1.0	-1.75	-2.2	V
Drain Course On State Besistance	R _{DS(ON)}	V _{GS} =-10V, I _D =-15A	-	8	10	mΩ
Drain-Source On-State Resistance		V _{GS} =-4.5V, I _D =-8A	-	11.5	15	mΩ
Forward Transconductance	g fs	V _{DS} =-5V,I _D =-15A	30	-	-	S
Dynamic Characteristics (Note4)			•			
Input Capacitance	C _{lss}	\/ - 15\/\/ -0\/	-	2900	-	PF
Output Capacitance	Coss	V_{DS} =-15V, V_{GS} =0V, F=1.0MHz	-	410	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.UNIFIZ	-	280	-	PF
Switching Characteristics (Note 4)			•			
Turn-on Delay Time	t _{d(on)}		-	15	-	nS
Turn-on Rise Time	t _r	V _{DD} =-15V, ID=-10A,	-	11	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =-10V, R_{GEN} =3 Ω	-	44	-	nS
Turn-Off Fall Time	t _f		-	21	-	nS
Total Gate Charge	Qg		-	48	-	nC
Gate-Source Charge	Q _{gs}	V _{DS} =-15V,I _D =-10A,V _{GS} =-10V	-	12	-	nC
Gate-Drain Charge	Q_{gd}		-	14	-	nC
Drain-Source Diode Characteristics	•		•	•		
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =-2A	-	-	-1.2	V

Notes

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production



Typical Electrical and Thermal Characteristics

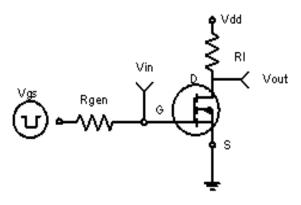
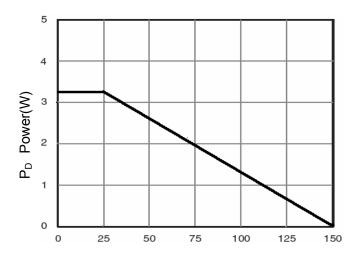


Figure 1 Switching Test Circuit



 T_J -Junction Temperature(°C) Figure 3 Power Dissipation

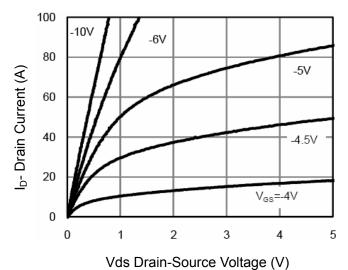


Figure 5 Output Characteristics

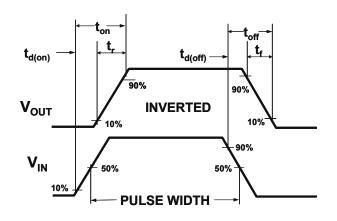


Figure 2 Switching Waveforms

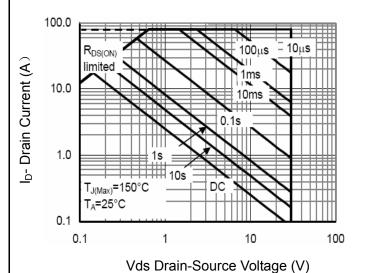


Figure 4 Safe Operation Area

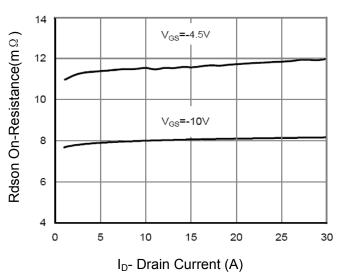


Figure 6 Drain-Source On-Resistance



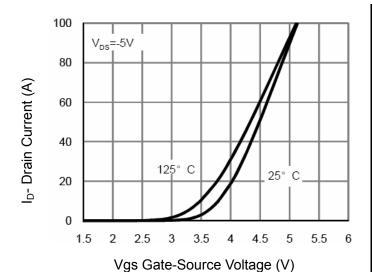
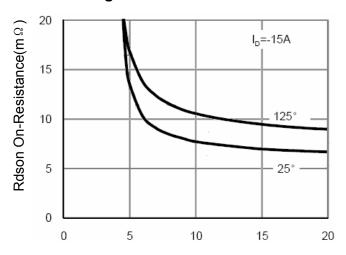


Figure 7 Transfer Characteristics



Vgs Gate-Source Voltage (V)
Figure 9 Rdson vs Vgs

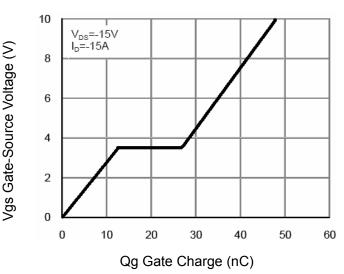
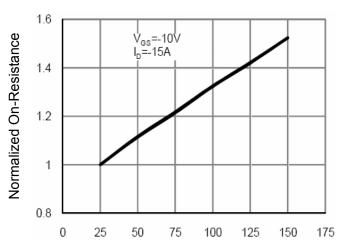


Figure 11 Gate Charge



T_J-Junction Temperature(℃)

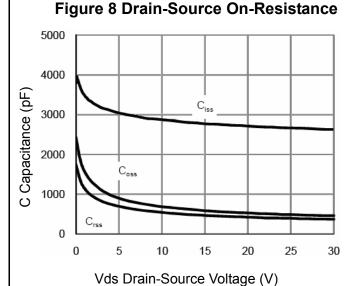


Figure 10 Capacitance vs Vds

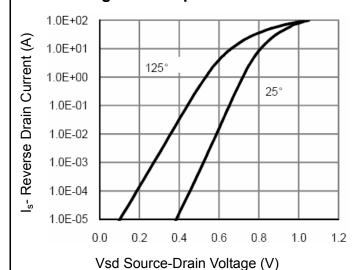


Figure 12 Source- Drain Diode Forward



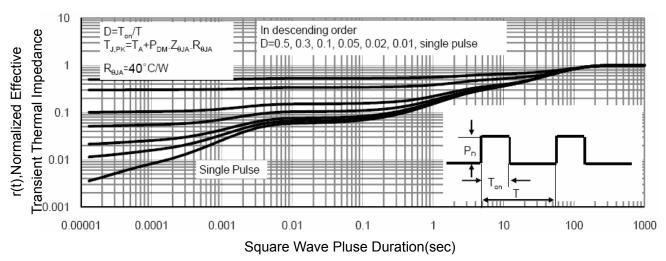
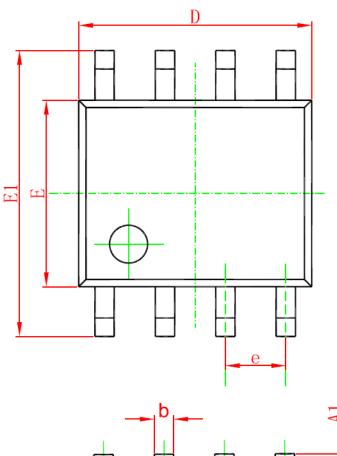
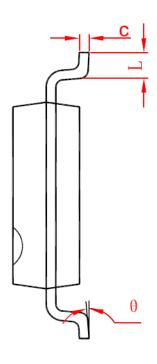


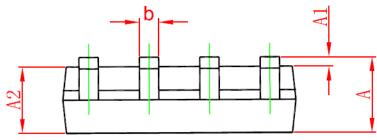
Figure 13 Normalized Maximum Transient Thermal Impedance



SOP-8 Package Information







Ch l	Dimensions In	n Millimeters	Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	1. 350	1. 750	0. 053	0. 069	
A1	0. 100	0. 250	0.004	0. 010	
A2	1. 350	1. 550	0. 053	0. 061	
b	0. 330	0. 510	0. 013	0. 020	
С	0. 170	0. 250	0.006	0. 010	
D	4. 700	5. 100	0. 185	0. 200	
Е	3. 800	4. 000	0. 150	0. 157	
E1	5. 800	6. 200	0. 228	0. 244	
е	1. 270	(BSC)	0. 050 (BSC)		
L	0. 400	1. 270	0. 016	0. 050	
θ	0°	8°	0°	8°	





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